

What is claimed is:

1 *Sub A2* 1. A laminate support used in the process of wire
2 bonding a circuit device, comprising a closed woven mesh
3 having strands whose separation distance is equal to or less
4 than the diameter of said wire of said circuit device.

1 2. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 1, wherein
3 said separation distance is no greater than 0.7 mils.

1 3. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 1, wherein
3 said separation distance is between 0.2 and 0.7 mils.

1 *Sub A3* 4. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 1, wherein
3 said laminate support comprises fiberglass.

1 *Sub A3* 5. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 1, wherein
3 said laminate support is between approximately 2.5 and 4
4 mils thick.

1 ~~5Vp~~ 11. The laminate support used in the process of wire
 2 bonding a circuit device in accordance with claim 7, wherein
 3 said laminate support is between approximately 2.5 and 4
 4 mils thick.

1 12. The laminate support used in the process of wire
 2 bonding a circuit device in accordance with claim 7, wherein
 3 said circuit device comprises a pad of large scale
 4 integrated design.

1 13. A laminate support used in the process of wire
 2 bonding a circuit device, comprising a closed woven mesh
 3 having warp and weave strands, whose separation distance is
 4 no greater than the diameter of said wire of said circuit
 5 device as measured lengthwise through said closed woven
 6 mesh, and wherein said separation distance is approximately
 7 equal to or less than 0.7 mils.

1 14. The laminate support used in the process of wire
 2 bonding a circuit device in accordance with claim 13,
 3 wherein said separation distance is between 0.2 and 0.7
 4 mils.

1 19. The method of claim 18, wherein said separation
2 distance is approximately equal to or less than 0.7 mils.

1 20. The method of claim 18, wherein said separation
2 distance is between approximately 0.2 and 0.7 mils.

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